

E 55/28/21
Core and accessories

Series/Type: B66335, B66252

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E 55/28/21 Core B66335

- To IEC 63093-8
- Delivery mode: single units

Magnetic characteristics (per set)

 $\Sigma I/A = 0.35 \text{ mm}^{-1}$

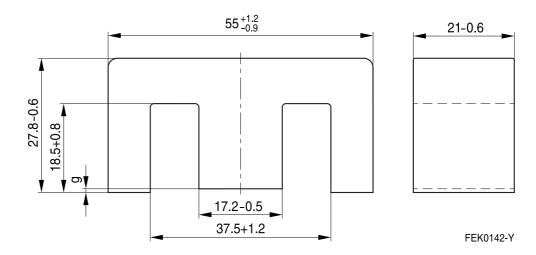
 $I_e = 124 \text{ mm}$

 $A_e = 354 \text{ mm}^2$

 $A_{min} = 351 \text{ mm}^2$

 $V_e = 43900 \text{ mm}^3$

Approx. weight 215g/set



Ungapped

Material	A _L value nH	μ _e	B _S ¹⁾ mT	P _V W/set	Ordering code
N27	5800 +30/–20%	1610	320	< 8.00 (200 mT, 25 kHz, 100 °C)	B66335G0000X127
N87	6400 +30/–20%	1780	320	< 3.80 (100 mT, 100 kHz, 100 °C)	B66335G0000X187
N97	6700 +30/–20%	1870	320	< 3.34 (100 mT, 100 kHz, 100 °C)	B66335G0000X197
N88	5700 +30/-20%	1590	320	< 4.50 (100 mT, 100 kHz, 120 °C)	B66335G0000X188

 $^{^{1)}}$ H = 250 A/m; f = 10 kHz; T = 100 °C

Gapped (A_L values/air gaps examples)

Material	g mm	A _L value approx. nH	μ_{e}	Ordering code ** = 27 (N27) = 87 (N87)
N27,	0.50 ±0.05	843	234	B66335G0500X1**
N87	1.00 ±0.05	496	138	B66335G1000X1**
	1.50 ±0.05	364	101	B66335G1500X1**
	2.00 ±0.05	292	81	B66335G2000X1**

The A_L value in the table applies to a core set comprising one ungapped core (dimension g = 0 mm) and one gapped core (dimension g > 0 mm).

Other A_L values/air gaps and materials available on request – see *Processing remarks on page 5*.



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Core B66335

Calculation factors (for formulas, see "E cores: general information")

Material	Relationship between air gap – A _L value		Calculation of saturation current			
	K1 (25 °C)	K2 (25 °C)	K3 (25 °C)	K4 (25 °C)	K3 (100 °C)	K4 (100 °C)
N27	496	-0.764	836	-0.847	781	-0.865
N87	496	-0.764	800	-0.796	765	-0.873

Validity range: K1, K2: 0.15 mm < s < 3.50 mm

K3, K4: 180 nH < A_L < 1799 nH



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Accessories B66252

Coil former

Material: GFR 6 polyamide (UL 94 V-0, insulation class to IEC 60085:

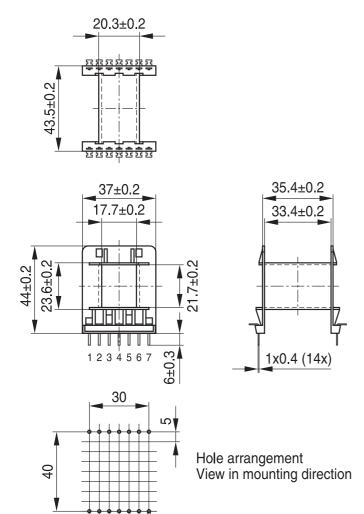
F = max. operating temperature 155 °C), color code natural

Durethan BKV 30H [E245249 (M)], LANXESS AG

Solderability: to IEC 60068-2-20, test Ta, method 1 (aging 3): 235 °C, 2 s

Resistance to soldering heat: to IEC 60068-2-20, test Tb, method 1B: 250 °C, 3.5 s

Sections	A _N	I _N	A _R value	Pins	Ordering code
	mm ²	mm	μΩ		
1	280	113	14	14	B66252B0000M001



1.6+0.1

FEK0752-6-E



Cautions and warnings

Mechanical stress and mounting

Ferrite cores have to meet mechanical requirements during assembling and for a growing number of applications. Since ferrites are ceramic materials one has to be aware of the special behavior under mechanical load.

As valid for any ceramic material, ferrite cores are brittle and sensitive to any shock, fast temperature changing or tensile load. Especially high cooling rates under ultrasonic cleaning and high static or cyclic loads can cause cracks or failure of the ferrite cores.

For detailed information see data book, chapter "General - Definitions, 8.1".

Effects of core combination on AL value

Stresses in the core affect not only the mechanical but also the magnetic properties. It is apparent that the initial permeability is dependent on the stress state of the core. The higher the stresses are in the core, the lower is the value for the initial permeability. Thus the embedding medium should have the greatest possible elasticity.

For detailed information see data book, chapter "General - Definitions, 8.1".

Heating up

Ferrites can run hot during operation at higher flux densities and higher frequencies.

NiZn-materials

The magnetic properties of NiZn-materials can change irreversible in high magnetic fields.

Ferrite Accessories

Our ferrite accessories have been designed and evaluated only in combination with our ferrite cores. We explicitly point out that our ferrite accessories or our ferrite cores may not be compatible with those of other manufacturers. Any such combination requires prior testing by the customer and will be at the customer's own risk.

We assume no warranty or reliability for the combination of our ferrite accessories with cores and other accessories from any other manufacturer.

Processing remarks

The start of the winding process should be soft. Else the flanges may be destroyed.

- Too strong winding forces may blast the flanges or squeeze the tube that the cores can not be mounted any more.
- Too long soldering time at high temperature (>300 °C) may effect coplanarity or pin arrangement.
- Not following the processing notes for soldering of the J-leg terminals may cause solderability problems at the transformer because of pollution with Sn oxyde of the tin bath or burned insulation of the wire. For detailed information see chapter "Processing notes", section 2.2.
- The dimensions of the hole arrangement have fixed values and should be understood as a recommendation for drilling the printed circuit board. For dimensioning the pins, the group of holes can only be seen under certain conditions, as they fit into the given hole arrangement.
 To avoid problems when mounting the transformer, the manufacturing tolerances for positioning the

customers' drilling process must be considered by increasing the hole diameter.



Cautions and warnings

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Symbols and terms

Symbol	Meaning	Unit
A	Cross section of coil	mm ²
A_{e}	Effective magnetic cross section	mm ²
A_L	Inductance factor; A _L = L/N ²	nH
A_{L1}	Minimum inductance at defined high saturation ($\triangleq \mu_a$)	nH
A _{min}	Minimum core cross section	mm ²
A _N	Winding cross section	mm ²
A_{R}	Resistance factor; $A_R = R_{Cu}/N^2$	$\mu\Omega$ = 10 ⁻⁶ Ω
В	RMS value of magnetic flux density	Vs/m ² , mT
ΔΒ	Flux density deviation	Vs/m ² , mT
Ê	Peak value of magnetic flux density	Vs/m ² , mT
ΔÂ	Peak value of flux density deviation	Vs/m ² , mT
B _{DC}	DC magnetic flux density	Vs/m², mT
B _R	Remanent flux density	Vs/m ² , mT
B _S	Saturation magnetization	Vs/m ² , mT
C_0	Winding capacitance	F = As/V
CDF	Core distortion factor	mm ^{-4.5}
DF	Relative disaccommodation coefficient DF = d/μ_i	
d	Disaccommodation coefficient	
Ea	Activation energy	J
f	Frequency	s ⁻¹ , Hz
f _{cutoff}	Cut-off frequency	s ^{−1} , Hz
f _{max}	Upper frequency limit	s−1, Hz
f _{min}	Lower frequency limit	s−1, Hz
f _r	Resonance frequency	s ^{−1} , Hz
f_Cu	Copper filling factor	
g	Air gap	mm
H	RMS value of magnetic field strength	A/m
Ĥ	Peak value of magnetic field strength	A/m
H_DC	DC field strength	A/m
H _c	Coercive field strength	A/m
h	Hysteresis coefficient of material	10 ^{−6} cm/A
h/μ _i 2	Relative hysteresis coefficient	10 ⁻⁶ cm/A
I	RMS value of current	Α
I _{DC}	Direct current	A
Î	Peak value of current	A
J	Polarization	Vs/m ²
k	Boltzmann constant	J/K
k ₃	Third harmonic distortion	
k _{3c}	Circuit third harmonic distortion	
L	Inductance	H = Vs/A



Symbols and terms

Symbol	Meaning	Unit
ΔL/L	Relative inductance change	Н
L_0	Inductance of coil without core	Н
L_H	Main inductance	Н
L_p	Parallel inductance	Н
L _{rev}	Reversible inductance	Н
L_s	Series inductance	Н
l _e	Effective magnetic path length	mm
I _N	Average length of turn	mm
N	Number of turns	
P_{Cu}	Copper (winding) losses	W
P _{trans}	Transferrable power	W
P_V	Relative core losses	mW/g
PF	Performance factor	
Q	Quality factor (Q = ω L/R _s = 1/tan δ _L)	
R	Resistance	Ω
R_{Cu}	Copper (winding) resistance (f = 0)	Ω
R_h	Hysteresis loss resistance of a core	Ω
ΔR_h	R _h change	Ω
R_i	Internal resistance	Ω
R_p	Parallel loss resistance of a core	Ω
R_s	Series loss resistance of a core	Ω
R_{th}	Thermal resistance	K/W
R_V	Effective loss resistance of a core	Ω
S	Total air gap	mm
T	Temperature	°C
ΔT	Temperature difference	K
T_C	Curie temperature	°C
t	Time	S
t_{V}	Pulse duty factor	
tan δ	Loss factor	
tan δ_L	Loss factor of coil	
tan δ_r	(Residual) loss factor at $H \rightarrow 0$	
tan δ_e	Relative loss factor	
tan δ_{h}	Hysteresis loss factor	
$tan \ \delta/\mu_i$	Relative loss factor of material at $H \rightarrow 0$	
U	RMS value of voltage	V
Û	Peak value of voltage	V
V_e	Effective magnetic volume	mm ³
Z	Complex impedance	Ω
Z_n	Normalized impedance $ Z _n = Z / N^2 \times \epsilon (_e/A_e)$	Ω /mm



Symbols and terms

Symbol	Meaning	Unit
α	Temperature coefficient (TK)	1/K
α_{F}	Relative temperature coefficient of material	1/K
α_{e}	Temperature coefficient of effective permeability	1/K
ε_{r}	Relative permittivity	
Φ	Magnetic flux	Vs
η	Efficiency of a transformer	
η_{B}	Hysteresis material constant	mT-1
η _i	Hysteresis core constant	$A^{-1}H^{-1/2}$
$\lambda_{\sf s}$	Magnetostriction at saturation magnetization	
μ	Relative complex permeability	
μ_0	Magnetic field constant	Vs/Am
μ _a	Relative amplitude permeability	
$\mu_{\sf app}$	Relative apparent permeability	
μ_{e}	Relative effective permeability	
μ_{i}	Relative initial permeability	
μ _p '	Relative real (inductive) component of $\overline{\mu}$ (for parallel components)	
μ _p "	Relative imaginary (loss) component of $\overline{\mu}$ (for parallel components)	
μ_{r}	Relative permeability	
μ_{rev}	Relative reversible permeability	
μ _s '	Relative real (inductive) component of $\overline{\mu}$ (for series components)	
μ _s "	Relative imaginary (loss) component of $\overline{\mu}$ (for series components)	
μ_{tot}	Relative total permeability derived from the static magnetization curve	
ρ	Resistivity	Ω m $^{-1}$
ΣI/A	Magnetic form factor	mm ⁻¹
τ _{Cu}	DC time constant $\tau_{Cu} = L/R_{Cu} = A_L/A_R$	s
ω	Angular frequency; ω = 2 Π f	s ⁻¹

Note:

All dimensions are given in mm.



Surface-mount device





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Important notes

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